

DATA SHEET

LCD MODULE

MODULE NO.:

TGG12864-68 SERIES

Customer:		
Approved by:		

Sonytek Display Co., Ltd.						
Approved by	Checked by	Prepared by				

RECORDS OF REVISION

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TGG12864-68B 02	Add 68B	Oct. 08th, 2016
TGG12864-68B 02	Add 68B	Oct. 08th, 2016

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1. FUNCTIONS & FEATURES

• TGG12864-68 Series LCD type:

Module	LCD Type	Remark
TGG12864-68A	FSTN Transflective Positive Mode	
TGG12864-68B	STN-Blue Transimmive Negative Mode	

• Display Contents : 128 x 64 Dots

• Driving Scheme : 1/65Duty; 1/9Bias

• Viewing Direction : 6 O' clock

• Power Supply Voltage : 3.0V.

• Driver IC : ST7565R-G

• Interface : Parallel & SPI

• Backlight :White

• Operating Temperature :- $20^{\circ}\text{C} - + 70^{\circ}\text{C}$

• Storage Temperature :-30°C - + 80°C

RoHS Compliant

Version: 02

2. MECHANICAL SPECIFICATIONS

• Outline Dimensions : 77.40(W) x 52.40(L) x 6.50(H)(mm)

• Viewing Area : 70.00 (W) x 40.00(L)(mm)

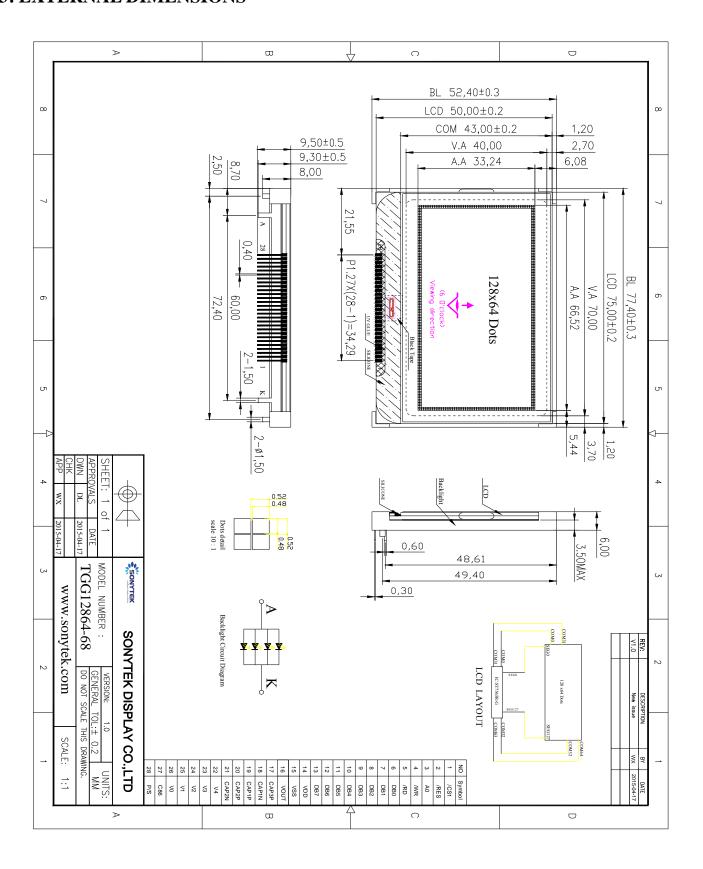
• Active Area : 66.52 (W) x 33.24 (L)(mm)

• Dot Pitch : 0.52 (W) x 0.52 (L)(mm)

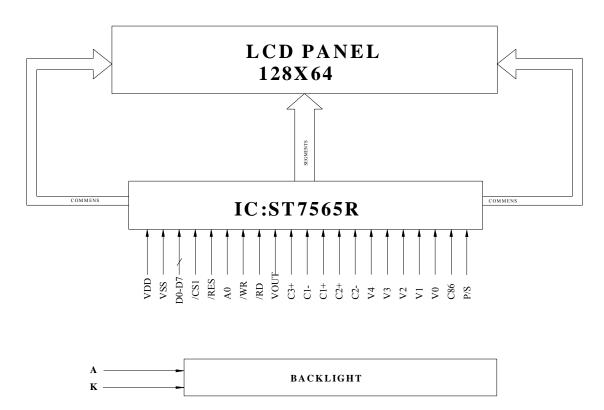
• Dot Size : 0.48 (W) x 0.48 (L)(mm)

• Weight : 35mg

3. EXTERNAL DIMENSIONS



4. BLOC`K DIAGRAM



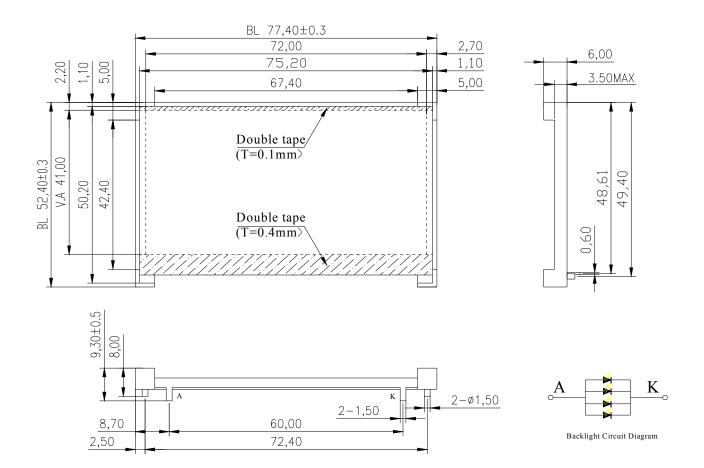
5. PIN ASSIGNMENT

Pin No.	Symbol	Function
1	/CS1	This is the chip select signal.
2	/DEC	When /RES is set to "L", the register settings are initialized (cleared).
2	/RES	The reset operation is performed by the /RES signal level.
		This is connect to the least significant bit of the normal MPU address bus, and it
3	A0	determines whether the data bits are data or command.
3	AU	A0 = "H": Indicates that D0 to D7 are display data.
		A0 = "L": Indicates that D0 to D7 are control data.
		• When connected to 8080 series MPU, this pin is treated as the "/WR" signal of the 8080
		MPU and is LOW-active.
		The signals on the data bus are latched at the rising edge of the /WR signal.
4	/WR(R/W)	• When connected to 6800 series MPU, this pin is treated as the "R/W" signal of the 6800
		MPU and decides the access type :
		When $R/W = "H"$: Read.
		When R/W = "L": Write.
		• When connected to 8080 series MPU, this pin is treated as the "/RD" signal of the 8080
		MPU and is LOW-active.
5	/DD(E)	The data bus is in an output status when this signal is "L".
3	/RD(E)	• When connected to 6800 series MPU, this pin is treated as the "E" signal of the 6800
		MPU and is HIGH-active.
		This is the enable clock input terminal of the 6800 Series MPU.
		This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus.
		When the serial interface (SPI-4) is selected ($P/S = L$ "):
6-13	D0-D7	D7: serial data input (SI); D6: the serial clock input (SCL).
		D0 to D5 should be connected to VDD or floating.
		When the chip select is not active, D0 to D7 are set to high impedance.
14	VDD	Power terminal of module
15	VSS	Ground terminal of module.
16	VOUT	DC/DC voltage converter. Connect a capacitor between this terminal and VSS or VDD terminal.
17	CAP3P	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP3P terminal.
18	CAP1N	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
19	CAP1P	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1P terminal.
20	CAP2P	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2P terminal.
21	CAP2N	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.
22	V4	This is a multi-level power supply for the liquid crystal drive. The voltage Supply applied is
23	V3	determined by the liquid crystal cell, and is changed through the use of a resistive voltage
24	V2	divided or through changing the impedance using an op. amp. Voltage levels are
25	V1	determined based on Vss, and must maintain the relative magnitudes shown below.
26	V0	$V0 \ge V1 \ge V2 \ge V3 \ge V4 \ge V_{SS}$
		This is the MPU interface selection pin.
27	C86	C86 = "H": 6800 Series MPU interface. C86 = "L": 8080 Series MPU interface.
		This pin configures the interface to be parallel mode or serial mode.
28	P/S	P/S = "H": Parallel data input/output. P/S = "L": Serial data input.
	A	Anode of Backlight
	K	Cathode of Backlight
	12	Cumous of Bushingin

6. BACKLIGHT ELECTRICAL/OPTICAL SPECIFICATIONS

Electrical/Optical Specifications

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Forward Voltage	Vf	2.9	3.1	3.3	V	If= 15 x4 mA
Reverse Current	Ir			120	mA	Vr=5.0 V
Power Dissipation	Pd			275	mW	If= 15 x4 mA
Dominant wave length	X		0.299	0.33		If= 15 x 4 mA
	Y		0.313	0.33	-	II- 13 X 4 IIIA
Luminous	Lv	220	250		cd/m ²	If= 15 x 4 mA
Luminous Uniformity	△Lv	70			%	If= 15 x 4 mA



NOTES:

- 1. Unmarked tolerance is ± 0.2
- 2. All materials comply with RoHS
- 3. Color: White
- 4.4 PCS LEDS

7. MAXIMUM ABSOLUTE POWER RATINGS

Item	Symbol	Standard value	Unit
Power supply voltage(1)	V_{DD}	-0.3~+3.6	V
Power supply voltage(2)	$V_{OUT,,}V_{0,}$	-0.3 ~ 13.5	V
Power supply voltage(3)	V _{IN}	-0.3 ~ V0	V
Operating temperature	Topr	-20~+70	°C
Storage temperature	Tstg	-30~+80	C

^{*}Voltage greater than above may damage to the Circuit.

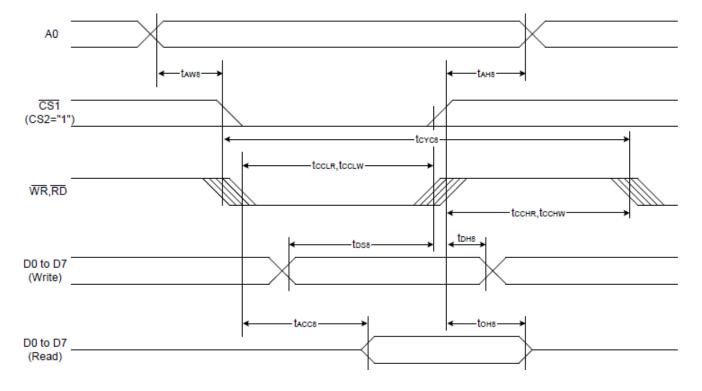
8. ELECTRICAL CHARACTERISTICS

8-1 DC Characteristics

Item	Cymbol	Standard Value			Test	Unit	
Item	Symbol	Min	Тур	Max	Condition	Omi	
Operating Voltage	V _{DD} -V _{SS}	2.8	3.0	3.2	TA=25℃	V	
Supply Current	I_{DD}		TBD	5.0		mA	
LCD Driving Voltage	V ₀ -V _{ss}	8.8	9.0	9.2	TA=25℃	V	

8-2 AC Characteristics

8.2.1 Read/Write mode for the 8080 Series MPU

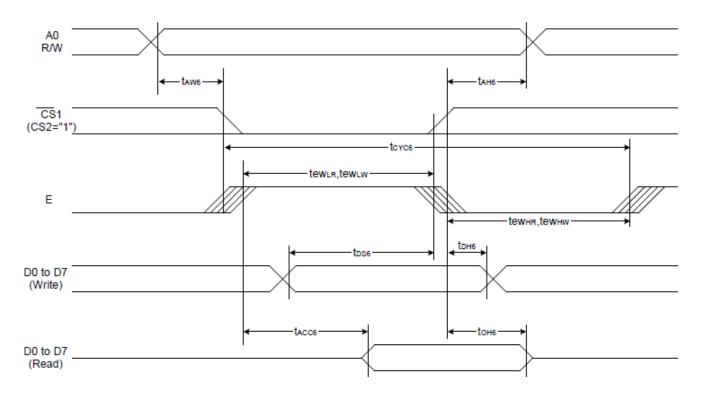


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lt	Cianal	S. m. b. a.l	Condition	Rat	ing	Units
ltem	Signal	Symbol	Condition	Min.	Max.	Units
Address hold time		tahs		0	_	
Address setup time	A0	taws		0	_	
System cycle time]	tcycs		240	_	
Enable L pulse width (WRITE)	WR	tccLw		80	_	
Enable H pulse width (WRITE)	WK	tсснw		80	_	
Enable L pulse width (READ)	RD	tcclr		140	_	Ns
Enable H pulse width (READ)	, KD	tcchr		80		
WRITE Data setup time		toss		40	_	
WRITE Address hold time	D0 to D7	tонв		0	_]
READ access time	1 00 10 07	taccs	CL = 100 pF	_	70	
READ Output disable time]	tонв	CL = 100 pF	5	50	

^{*1} The input signal rise time and fall time (t_r, t_f) is specified at 15 ns or less. When the system cycle time is extremely fast, $(t_r + t_f) \le (t_{CYCS} - t_{CCLW})$ for $(t_r + t_f) \le (t_{CYCS} - t_{CCLR})$ are specified.

8.2.2 Read/Write mode for the 6800 Series MPU



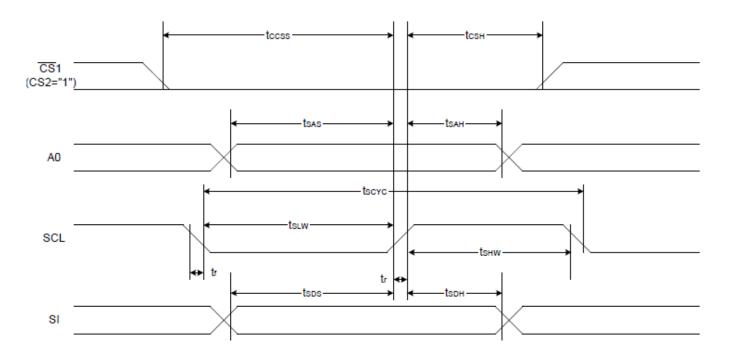
^{*2} All timing is specified using 20% and 80% of Voo as the reference.

^{*3} tccLw and tccLR are specified as the overlap between /CS1 being "L" (CS2 = "H") and /WR and /RD being at the "L" level.

Itam	Cianal	Comb of	Condition	Rating		Units
Item	Signal	Symbol	Condition	Min.	Max.	Max.
Address hold time		tahв		0	_	
Address setup time	A0	taw6		0	_	
System cycle time		tcyce		240	_]
Enable L pulse width (WRITE)	WR	tewLw		80	_]
Enable H pulse width (WRITE)	T WK	tеwнw		80	_]
Enable L pulse width (READ)	RD	tewlr		80	_	ns
Enable H pulse width (READ)	T KD	tewnr		140]
WRITE Data setup time		tose		40	_]
WRITE Address hold time	D0 40 D7	tоне		0	_]
READ access time	D0 to D7	tacce	CL = 100 pF	_	70]
READ Output disable time]	tонв	CL = 100 pF	5	50]

^{*1} The input signal rise time and fall time (tr, tr) is specified at 15 ns or less. When the system cycle time is extremely fast, (tr+tr) ≤ (tcycs - tewnw) for (tr+tr) ≤ (tcycs - tewnw) are specified.

8.2.3 The 4-line SPI Interface



^{*2} All timing is specified using 20% and 80% of Vod as the reference.

^{*3} tewsw and tewsr are specified as the overlap between CS1 being "L" (CS2 = "H") and E.

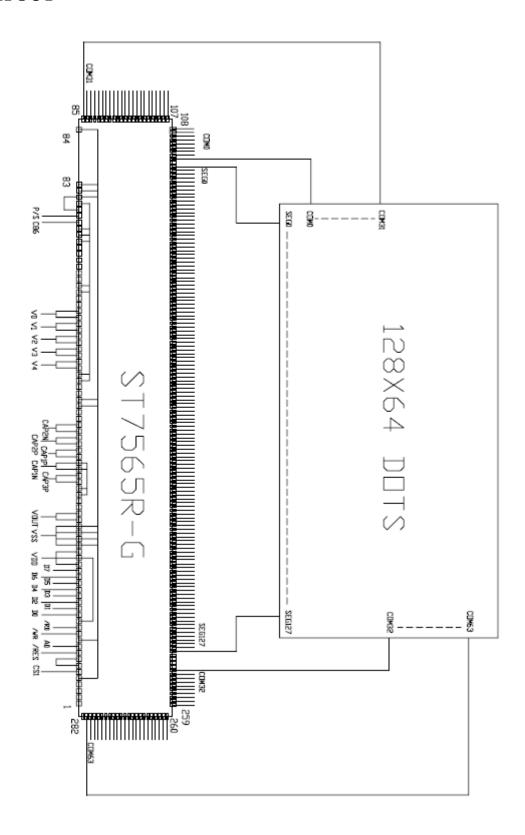
Item	Signal	Symbol	Condition	Rat	ing	Units
item	Signal	Symbol	Condition	Min.	Max.	Units
4-line SPI Clock Period		Tscyc		50	_	
SCL "H" pulse width	SCL	T _{shw}		25	_	
SCL "L" pulse width]	TsLw		25	_]
Address setup time	A0	Tsas		20	_]
Address hold time	T AU	Tsah		10	_	ns
Data setup time	- SI	T _{sds}		20	_]
Data hold time	31	Тѕон		10	_]
CS-SCL time	- CS	Toss		20	_]
CS-SCL time		Tcsh		40	_]

9. INSTRUCTION TABLE

Table of \$T7565P Commands	(Note) *: disabled data
Tubic of 3173031 Communas	(140tc) . disabled date

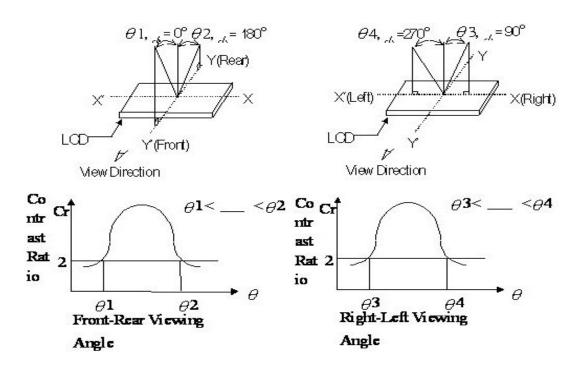
Table of \$T7565P Commands										(Note) *: disabled data		
Command	Command			Command Code							Function	
Communa	Α0	/RD	/WR		D6	D5	D4	D3	D2	D1		Tuncaon
(1) Display ON/OFF	0	1	0	1	0	1	0	1	1	1	0 1	LCD display ON/OFF 0: OFF, 1: ON
(2) Display start line set	0	1	0	0	1	Di	spla	ay sta	art a	ddre	ess	Sets the display RAM display start line address
(3) Page address set	0	1	0	1	0	1	1	Pa	ge a	ddr	ess	Sets the display RAM page address
(4) Column address set upper bit Column address set lower bit	0	1	0	0	0	0	0	colu Lea	umn ast si	add ignif	cant Iress icant Iress	Sets the most significant 4 bits of the display RAM column address. Sets the least significant 4 bits of the display RAM column address.
(5) Status read	0	0	1		St	atus		0	0	0	0	Reads the status data
(6) Display data write	1	1	0			١	Vrit	e da	ta			Writes to the display RAM
(7) Display data read	1	0	1			F	Rea	d da	ta			Reads from the display RAM
(8) ADC select	0	1	0	1	0	1	0	0	0	0	0 1	Sets the display RAM address SEG output correspondence 0: normal, 1: reverse
(9) Display normal/ reverse	0	1	0	1	0	1	0	0	1	1	0 1	Sets the LCD display normal/ reverse 0: normal, 1: reverse
(10) Display all points ON/OFF	0	1	0	1	0	1	0	0	1	0	0 1	Display all points 0: normal display 1: all points ON
(11) LCD bias set	0	1	0	1	0	1	0	0	0	1	0 1	Sets the LCD drive voltage bias ratio 0: 1/9 bias, 1: 1/7 bias (ST7565P)
(12) Read/modify/write	0	1	0	1	1	1	0	0	0	0	0	Column address increment At write: +1 At read: 0
(13) End	0	1	0	1	1	1	0	1	1	1	0	Clear read/modify/write
(14) Reset	0	1	0	1	1	1	0	0	0	1	0	Internal reset
(15) Common output mode select	0	1	0	1	1	0	0	0 1	*	*	*	Select COM output scan direction 0: normal direction 1: reverse direction
(16) Power control set	0	1	0	0	0	1	0	1		era ode	ting	Select internal power supply operating mode
(17) Vo voltage regulator internal resistor ratio set	0	1	0	0	0	1	0	0		sist itio	or	Select internal resistor ratio(Rb/Ra) mode
(18) Electronic volume mode set Electronic volume register set	0	1	0	1	0	0 Ele	0 ctro	0 nic v	0 olun	0 ne v	1 alue	Set the Vo output voltage electronic volume register
(19) Static indicator ON/OFF	0	1	0	1	0	1	0	1	1	0	0	0: OFF, 1: ON
Static indicator register set				0	0	0	0	0	0	0	Mode	Set the flashing mode
(20) Booster ratio set	0	1	0	1 0	1 0	1 0	1	1 0	0		0 p-up ilue	select booster ratio 00: 2x,3x,4x 01: 5x 11: 6x
(21) Power saver												Display OFF and display all points ON compound command
(22) NOP	0	1	0	1	1	1	0	0	0	1	1	Command for non-operation
(23) Test	0	1	0	1	1	1	1	*	*	*	*	Command for IC test. Do not use this command

10. IC LAYOUT

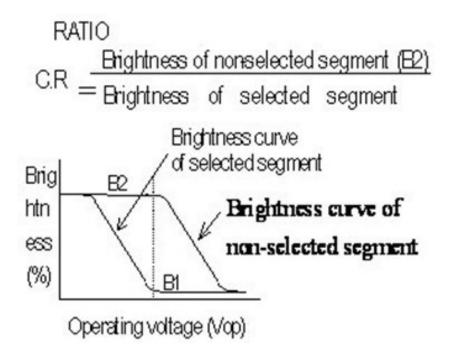


11. Optical Characteristics

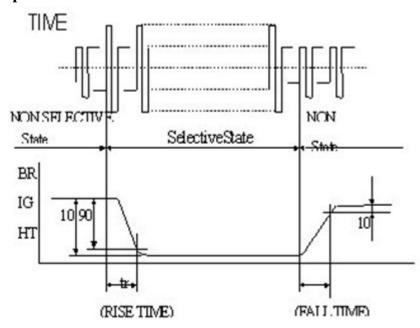
11.1 Definition of Viewing Angle



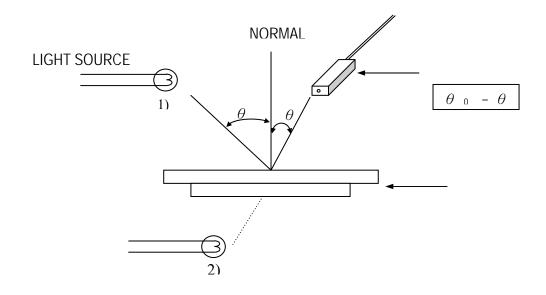
11.2 Definition of Contrast



11.3 Definition of Response



11.4 Measuring Instruments For Electro-optical Characteristics



* Note:

- 1) Light source position for measuring the reflective type of LCD panel;
- 2) Light source position for measuring the transflective / transmissive types of LCD panel.

12. MODULE ACCEPT QUALITY LEVEL (AQL)

12.1 AQL Standard Value: Critical Defect =0.1, Major Defect=0.65; Minor Defect =2.5.

12.2 Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level II

13. RELIABILITY TEST

Operating life time: Longer than 50,000 hours

(at room temperature without direct irradiation of sunlight)

Reliability characteristics shall meet following requirements.

No.	Test Item	Content of Test	Test Condition
1	High Temperature Storage	Endurance test applying the high storage temperature for a long time	+80°C 96H
2	Low Temperature Storage	Endurance test applying the low storage temperature for a long time	−30°C 96H
3	High Temperature Operation	Endurance test applying the electric stress (voltage & current) and the thermal stress to the element for a long time	+70°C 96H
4	Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time	−20°C 96H
5	High Temperature/ Humidity Storage	Endurance test applying the high temperature and humidity storage for a long time	60°C 90%RH 96H
6	Temperature Cycle	Endurance test applying the low and high temperature cycle $-20^{\circ}\text{C} \longleftrightarrow 25^{\circ}\text{C} \longleftrightarrow 70^{\circ}\text{C} \longleftrightarrow 25^{\circ}\text{C}$ 30min 5min 30min 5min $\longleftrightarrow 1 \text{ cycle}$	-20°C/70°C 5 cycles
7	Vibration Test (Package State)	Endurance test applying the vibration during transportation	10Hz-55Hz, 50m/s,15min
8	Shock Test (Package State)	Endurance test applying the shock during transportation	Half-sinewave, 100m/s, 11ms
9	Atmospheric Pressure Test	Endurance test applying the atmospheric pressure during transportation by air	40 kPa 16 H

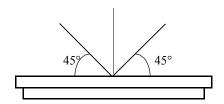
14. Packaging

TBD

15. Inspection specification

15.1 Visual Inspection

- 1) Inspect under 2x20W or 40W fluorescent lamp (approximately 3000 lux) leaving 25 to 30 cm between the module and the lamp and 30 cm between the module and the eye (measuring position).
- 2) Appearance is inspected at the best contrast voltage (best contrast is adjusted considering clearness and crosstalk on screen).
- 3) Inspect the module at 45° right and left, top and bottom.
- 4) Use the optimum viewing angle during the contrast inspection.



15.2 Standard of Appearance Inspection

No.	Item	Criteria								
		Round type: as per following drawing								
		•	$\Phi = (X+Y)/2$	Δ.	cceptable quantity					
				Size	Zone A	Zone B				
		e	\bigcirc	Ф<0.1	Any number					
			\$ `	0.1<Ф<0.2	2	Any number				
			X	0.2<Ф<0.25	1	Any number				
				0.25<Ф	0					
		I	Line type: as pe	r following drawing Accepta	ble quantity					
	Black spot		Length	Width	Zone A	Zone B				
1	White spot		_	W≤0.02	Any num ber	Any				
	Dust		L≤3.0	0.02 <w≤0.03< td=""><td></td><td>nu</td></w≤0.03<>		nu				
			L≤2.5	0.03 <w≤0.05< td=""><td>2</td><td>mb</td></w≤0.05<>	2	mb				
			_	0.05 <w< td=""><td>As round type</td><td>er</td></w<>	As round type	er				
		,	W L Total acceptable	e quantity: 3						
2	Polariser	5	Scratch on prote	ective film is permitte	ed					

	scratch	Scratch on polariser: sar	me as No. 1				
		$\Phi = (X+Y)/2$					
				Acceptable q	uıantity.		
		<u></u>	Size	Zone A		ne B	
		X	Size		1 Zui	пс Б	
				Any			
				nı			
	D - 1 i		Ф<0.2				
3	Polariser	Total acceptable		be			
	bubble	quantity: 3		r	A	ny	
		quantity. 3	0.2< Ф			nu	
			<0			mb	
			5			er	
			0.5< Ф	,			
			<1	. 1			
			0				
			1.0< Ф	0			
		4.1 Pin hole on segmen	ted display	•	<u> </u>		
		W: segment width					
		$\Phi = (A+B)/2$					
		- (11.13)/2					
		B → //← . →		Acceptable quar	ntity		
		B	Width	(Quantity		
				Ф ≤0.2		Φ	
		A	W≤0.4		≤1/2W		
				Ф ≤0.25			
		$\mathbf{\dot{w}}^{\prime}$	W>0.4	Φ <u>≤</u> 0.23 Φ≤1/3V			
			Total accenta				
		segr		ptable quantity: 1 defect per ent			
			5051110111	•			
		4.2 Pin hole on		with Φ under	0.10 mm	are	
		dot matrix	Pin holes	with Φ under	0.10 mm	are	
				with Φ under	0.10 mm	are	
		dot matrix	Pin holes	with Ф under ole			
	Segment	dot matrix	Pin holes acceptal	with © under ble Accep	0.10 mm		
4	deform	dot matrix display	Pin holes acceptal	with Ф under ole			
4		dot matrix display	Pin holes acceptal	with © under ble Accep	table quantit		
4	deform	dot matrix display	Pin holes acceptal	with © under ble Accep	table quantit	y	
4	deform	dot matrix display	Pin holes acceptal	with © under ble Accep	table quantit	y Any nu	
4	deform	dot matrix display	Pin holes acceptal	Acception Size	table quantit	y any nu m	
4	deform	dot matrix display	Pin holes acceptal	Acception Size	table quantit	y nu m be	
4	deform	dot matrix display	Pin holes acceptal	Acception Size	table quantit	y ny nu m be	
4	deform	dot matrix display	Pin holes acceptal	Acception Size	table quantit	nu m be r	
4	deform	dot matrix display	Pin holes acceptal	Acception Size a, b<0.1	table quantit	nu m be r	
4	deform	dot matrix display	Pin holes acceptal	Acception Size	table quantit	nu mu be r nny nu m	
4	deform	dot matrix display	Pin holes acceptal	Acception Size a, b<0.1	table quantit	nu m bee r nny nu m	
4	deform	dot matrix display	Pin holes acceptal	Acception Size a, b<0.1	table quantit	nu mu be r nny nu m	
4	deform	dot matrix display	Pin holes acceptal	Acception Size Acception Size Acception Size	table quantit	nu m bee r nny nu m	
4	deform	dot matrix display Total acceptable quantit 4.3 Segments / dots wit width	Pin holes acceptal	with ⊕ under ole Accept Size a, b<0.1 (a+b)/2≤0 0.5<⊕ <1.0	table quantit	nu m bee r mu bee r	
4	deform	dot matrix display	Pin holes acceptal	Acception Acception Acception Acception Acception Acception Acception Accepta	table quantit	nu m bee r nu bee r	
4	deform	dot matrix display Total acceptable quantit 4.3 Segments / dots wit width	Pin holes acceptal	with ⊕ under ole Accept Size a, b<0.1 (a+b)/2≤0 0.5<⊕ <1.0	table quantit	nu m bee r nu bee r	

312004-00		Ф=(А-	+B)/2				opecijica				
		(11	<i></i>								
		BY BY	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\								
						Acceptable quantity					
					Size						
		m		\sim		-	Any				
					⊅ <0.4		nu				
		≥		B	Φ≤0.4		m ha				
							be r				
			$C \square$		0.4<Ф		r				
					0. 4 \ ⊈ \ ≤1.		5				
		Total acc	ceptable quant	rity: 7	0						
		1 otal acc	ceptaore quan	ity. /	1.0<Ф						
					≤1.		3				
					5						
					1.5<Ф						
					≤ 2.		2				
					0						
	Colour										
5	unifor	Level of	sample for ap	proval set as li	mit sample						
	mity	771 1 1	1: 1 / 1	1 11	11	1 .					
	D1-1:-1-4	The backlight colour should correspond to the product specification									
6	Backlight	Flashing and or unlit backlight is not allowed Dust larger than 0.25 mm is not allowed									
		Exposed wire bond pad is not allowed									
7	COB	=	Insufficient covering with resin is not allowed (wire bond line								
,											
		exposed) Dust or bubble on the resin are not allowed No unmelted solder paste should be present on PCB									
		Cold solder joints, missing solder connections, or oxidation are not									
8	PCB	allowed									
		No residue or solder balls on PCB are allowed									
		Short cir	cuits on comp	onents are not	allowed						
			<u> </u>	Acceptable							
				Size	Q	uantity					
			On			Any					
			t	Ф<0.2	2	nu					
			r			mb					
	Tray		a	Ф×0.2	5	er					
9	particle		y On	$\Phi > 0.2$ $\Phi \geqslant 0.2$		2					
	S		On d	Ψ ≥0	۷.5						
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16. LCD MODULES HANDLING PRECAUTIONS

- Please remove the protection foil of polarizer before using.
- The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- If the display panel is damaged and the liquid crystal substance inside it leaks out, do not get any in your mouth. If the substance come into contact with your skin or clothes promptly wash it off using soap and water.
- Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarize carefully.
- To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - -Be sure to ground the body when handling the LCD module.
 - -Tools required for assembly, such as soldering irons, must be properly grounded.
 - -To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
 - -The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

■ Storage precautions

When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags designed to prevent static electricity charging under low temperature / normal humidity conditions (avoid high temperature / high humidity and low temperatures below 0

°C). Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

17. OTHERS

- Liquid crystals solidify at low temperature (below the storage temperature range) leading to defective orientation of liquid crystal or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subjected to a strong shock at a low temperature.
- If the LCD modules have been operating for a long time showing the same display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. Abnormal operating status can be resumed to be normal condition by suspending use for some time. It should be noted that this phenomena does not adversely affect performance reliability.
- To minimize the performance degradation of the LCD modules resulting from caused by static electricity, etc. exercise care to avoid holding the following sections when handling the modules:
 - Exposed area of the printed circuit board
 - Terminal electrode sections